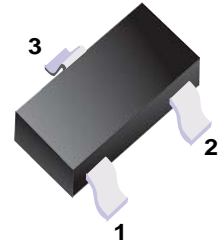


FTK1012C N-Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$
20V	380mΩ@4.5V
	620mΩ@2.5V



SOT-523

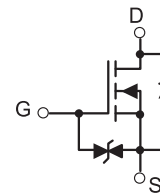
Feature

- High-Side Switching
- Low On-Resistance
- Low Threshold
- Fast Switching Speed
- ESD protected up to 2 KV

Applications

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

Equivalent Circuit



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current at $V_{GS} = 4.5\text{ V}$	I_D	700 ¹⁾ 440 ¹⁾	mA
Peak Drain Current, Pulsed ($t_p \leq 10\ \mu\text{s}$)	I_{DM}	2.8	A
Power Dissipation	P_D	300 ¹⁾	mW
Maximum Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	510 ²⁾	$^\circ\text{C/W}$
Junction Temperature Rang	T_j	- 55 to + 150	$^\circ\text{C}$
Storage Temperature Rang	T_{stg}	- 65 to + 150	$^\circ\text{C}$

¹⁾ Device mounted on an FR-4 (PCB), single-sided copper, tin-plated, mounting pad for drain 1 cm².

²⁾ Device mounted on an FR-4 (PCB), single-sided copper, tin-plated and standard footprint.



FTK1012C

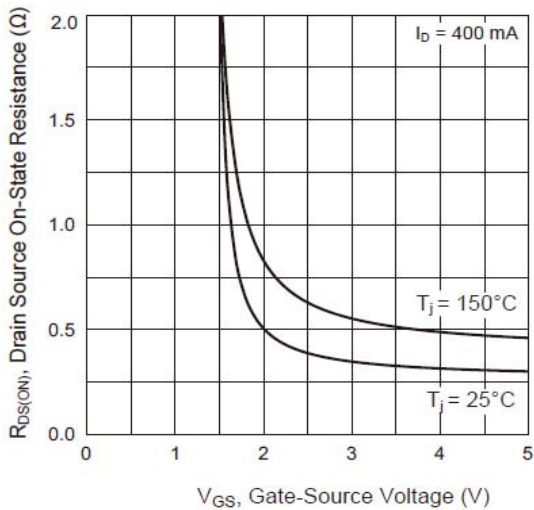
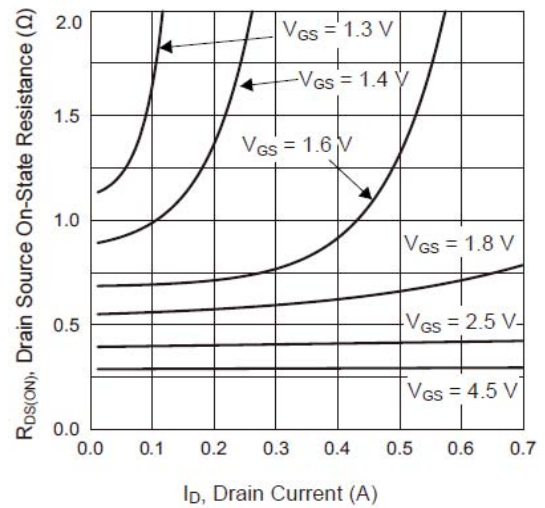
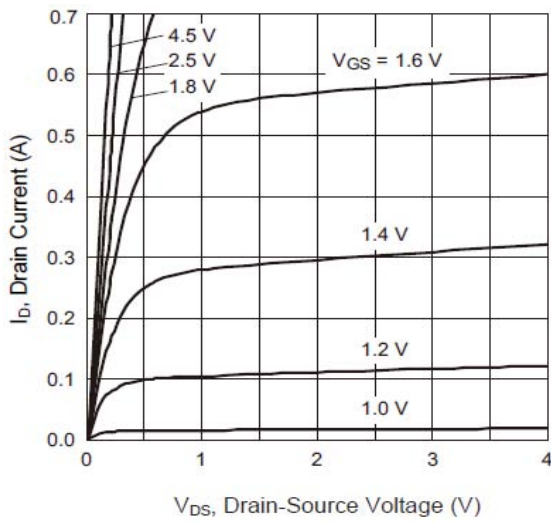
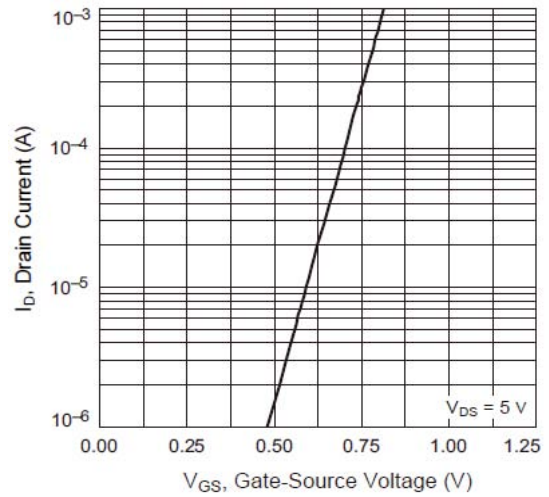
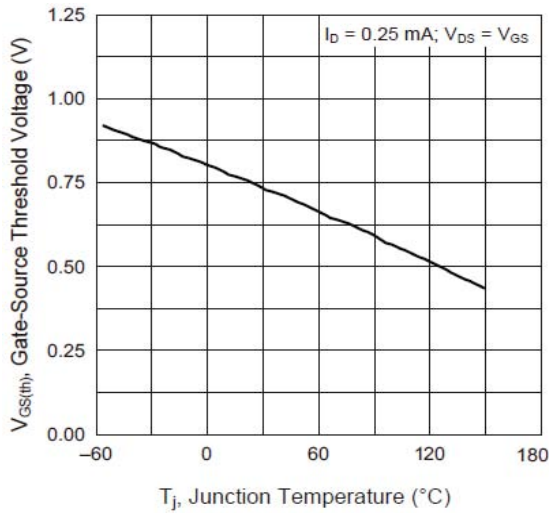
Electrical Characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	BV_{DSS}	20	-	-	V
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	V_{GSth}	0.5	-	0.95	V
Drain-Source Leakage Current at $V_{DS} = 20 \text{ V}$	I_{DSS}	-	-	1	μA
Gate Leakage Current at $V_{GS} = \pm 8 \text{ V}$ at $V_{GS} = \pm 4.5 \text{ V}$	I_{GSS}	- -	- -	± 2 ± 0.5	μA
Drain-Source On-State Resistance at $V_{GS} = 4.5 \text{ V}$, $I_D = 0.5 \text{ A}$ at $V_{GS} = 2.5 \text{ V}$, $I_D = 0.4 \text{ A}$ at $V_{GS} = 1.8 \text{ V}$, $I_D = 0.1 \text{ A}$	$R_{DS(on)}$	- - -	- - -	380 620 1100	$\text{m}\Omega$
Forward Transconductance at $V_{DS} = 10 \text{ V}$, $I_D = 0.2 \text{ A}$	$ g_{FS} $	-	1.6	-	S
Input Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 10 \text{ V}$, $f = 1 \text{ MHz}$	C_{iss}	-	-	83	pF
Output Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 10 \text{ V}$, $f = 1 \text{ MHz}$	C_{oss}	-	15	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 10 \text{ V}$, $f = 1 \text{ MHz}$	C_{rss}	-	7	-	pF
Turn-On Delay Time at $V_{GS} = 4.5 \text{ V}$, $V_{DS} = 10 \text{ V}$, $R_L = 250 \Omega$, $R_G = 6 \Omega$	t_{on}	-	-	12	ns
Turn-On Rise Time at $V_{GS} = 4.5 \text{ V}$, $V_{DS} = 10 \text{ V}$, $R_L = 250 \Omega$, $R_G = 6 \Omega$	t_r	-	4	-	ns
Turn-Off Delay Time at $V_{GS} = 4.5 \text{ V}$, $V_{DS} = 10 \text{ V}$, $R_L = 250 \Omega$, $R_G = 6 \Omega$	t_{off}	-	-	172	ns
Turn-Off Fall Time at $V_{GS} = 4.5 \text{ V}$, $V_{DS} = 10 \text{ V}$, $R_L = 250 \Omega$, $R_G = 6 \Omega$	t_{off}	-	31	-	ns
Diode Forward Voltage at $I_S = 0.3 \text{ A}$, $V_{GS} = 0 \text{ V}$	V_{SD}	0.48	-	1.2	V

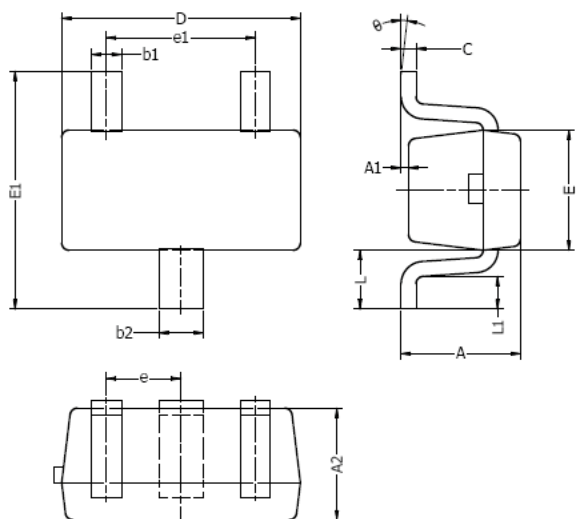


FTK1012C

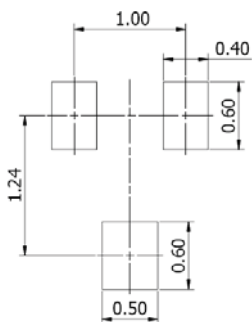
ELECTRICAL CHARACTERISTICS CURVES



OUTLINE AND DIMENSIONS



Typical Soldering Pattern:



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
A2	0.70	0.80	0.028	0.031
b1	0.15	0.25	0.006	0.010
b2	0.25	0.35	0.010	0.014
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
E1	1.45	1.75	0.057	0.069
e	0.50 TYP.		0.020 TYP.	
e1	0.90	1.10	0.035	0.043
L	0.40 REF.		0.016 REF.	
L1	0.10	0.30	0.004	0.012
θ	0°	8°	0°	8°

NOTES:

- Above package outline conforms to JEITA EAIJ ED-7500A SC-75.
- Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.